	L Number	Hits	Search Text	DB	Time stamp
	1	12731		USPAT;	2004/03/12 09:48
			(multiple multi) adj5 (module\$1 layer\$2)	US-PGPUB;	
				EPO; JPO	
1	2	2397	(packag\$3 same (chip\$1 die\$1 dice\$1) and	USPAT;	2004/03/12 10:02
			(multiple multi) adj5 (module\$1 layer\$2))	US-PGPUB;	
1			and (pcb\$2 circuit\$1 adj board\$1) near20	EPO; JPO	
			(si silicon semiconductor polysilicon)		
	3	278	((packag\$3 same (chip\$1 die\$1 dice\$1)	USPAT;	2004/03/12 09:53
-			and (multiple multi) adj5 (module\$1	US-PGPUB;	
			layer\$2)) and (pcb\$2 circuit\$1 adj	EPO; JPO	
			board\$1) near20 (si silicon semiconductor		
			polysilicon)) and (pcb\$2 circuit\$1 adj		
Ì			board\$1) near7 (si silicon semiconductor		
			polysilicon) and high adj frequency		
4	4	113	(((packag\$3 same (chip\$1 die\$1 dice\$1)	USPAT;	2004/03/12 10:02
			and_(multiple_multi) adi5 (module\$1	US-PGPUB;	
			layer\$2)) and (pcb\$2 circuit\$1 adj	EPO; JPO	
			board\$1) near20 (si silicon semiconductor		
			polysilicon)) and (pcb\$2 circuit\$1 adj		
			board\$1) near7 (si silicon semiconductor		
			polysilicon) and high adj frequency) and		:
1			signal same power same ground		
9	5	.113	1 2	USPAT;	2004/03/12 10:02
			and (multiple multi) adj5 (module\$1	US-PGPUB;	
			layer\$2)) and (pcb\$2 circuit\$1 adj	EPO; JPO	
			board\$1) near20 (si silicon semiconductor		
			polysilicon)) and (pcb\$2 circuit\$1 adj		
		9	board\$1) near7 (si silicon semiconductor		
			polysilicon) and high adj frequency) and		
			signal same power same ground) and (pcb\$2		
			circuit\$1 adj board\$1) near7 (si silicon		
			semiconductor polysilicon)		